



SN 09/583,599

Response to April 27, 2004 Office Action

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re patent application of: Wang et al.

Serial No.: 09/583,599

Group Art Unit: 1711

Filed: May 31, 2000

Examiner: Thao T. Tran

Attorney Docket: 99A209

Title: Improved Acid Copper Electroplating Solutions

COMMISSIONER FOR PATENTS

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SIR:

CERTIFICATE OF MAILING

I hereby certify that this correspondence and every writing referred to herein as being enclosed is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on MAY 27, 2004.  
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Betty Lee

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SUPPLEMENTAL

RESPONSE TO RESTRICTION REQUIREMENT

In response to the Notice of Non-Compliant Amendment dated April 27, 2004 and the non-final Office Action dated March 11, 2004 requiring correction of the amendments to the claims for failure to include a complete listing of all of the claims, Applicants submit the following corrected "Listing of Claims" section and Remarks.